



RoHS

广州亨光电子有限公司

Guangzhou Heng Guang Electronics Co.,Ltd

SPECIFICATION FOR APPROVAL

承认书

CUSTOMER'S CODE

客户代码

DESCRIPTION

品名

SMD

SPECIFICATION

规格

3030 WHITE 1W

DATE

送样日期

PART NO.

本厂型号

HG-W1030S12-3030

REFERENCE NO.

档案号

NUMBER OF SAMPLE

送样数量

PCS

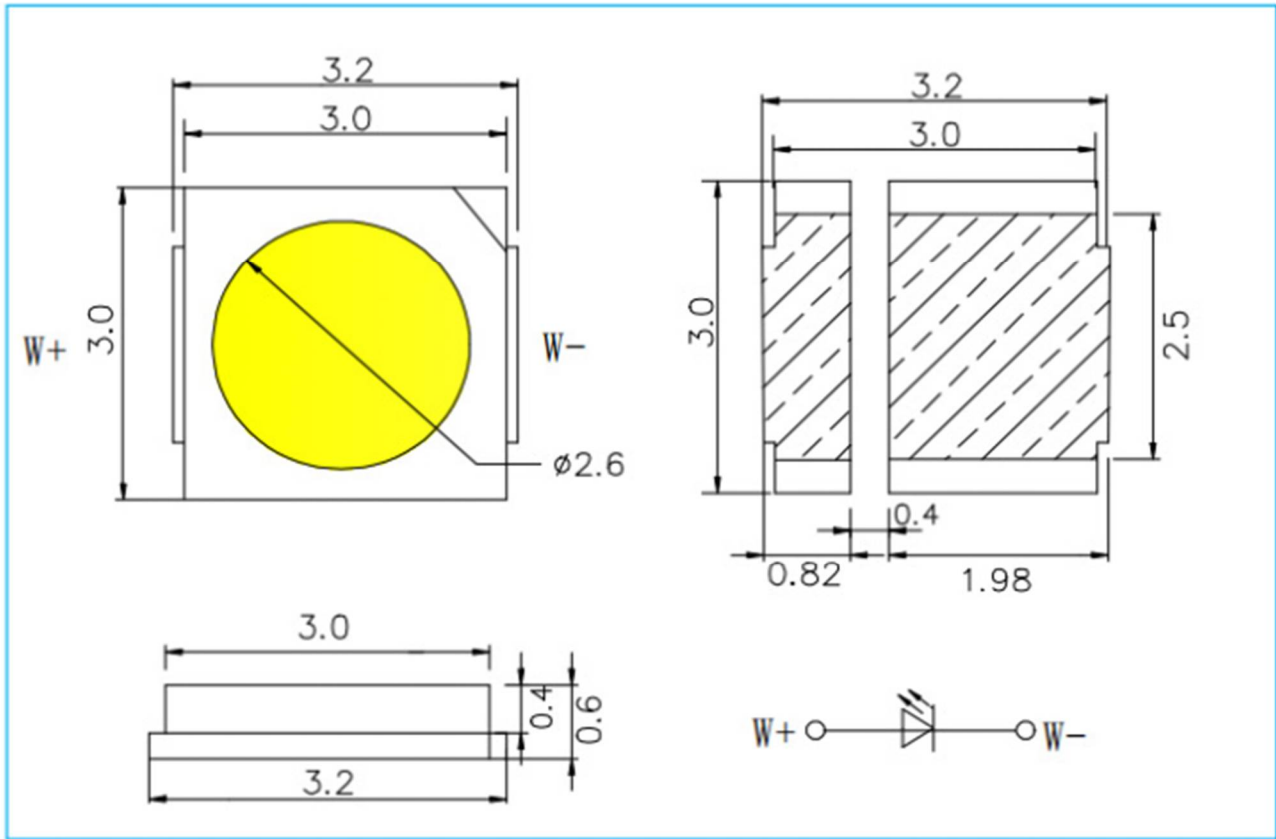
COPY OF ACKNOWLEDGEMENT

承认书份数

Approved By Customer 客户承认	Qualified By 核准	Form Designer 制作



Package Dimensions



Notes:

1. All dimensions are in mm.
2. Tolerance is ± 0.25 mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
HG-W1030S12-3030	GaP/GaP	White	Water Clear

Absolute Maximum Ratings at $T_a=25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	1000	mW
Reverse Voltage	VR	3	V
D.C. Forward Current	If	300	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	If(Peak)	350	mA
Operating Temperature Range	Topr.	-40 to +75	$^\circ\text{C}$
Storage Temperature Range	Tstg.	-40 to +75	$^\circ\text{C}$

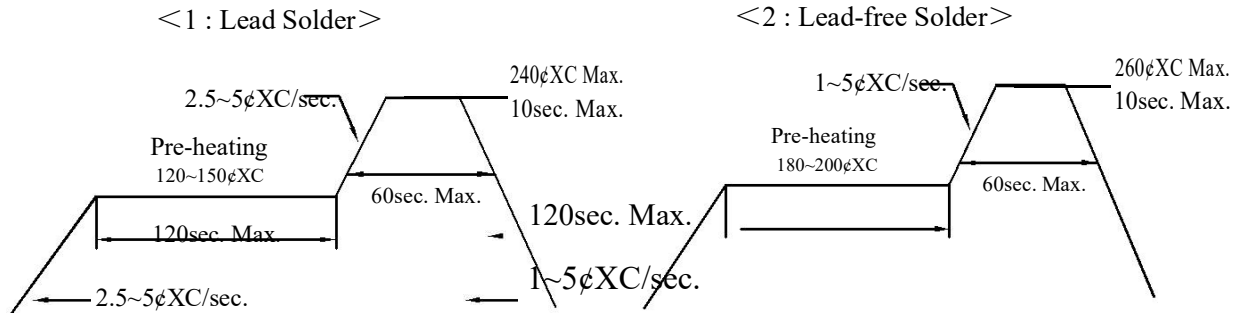


Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _f =300mA	6000	6500	7000	mcd
Luminous Flux	Φ _v	I _f =300mA	110		120	lm
Forward Voltage	V _f	I _f =300mA	3.0		3.2	V
Electrostatic Discharge	ESD		4000			V
Reverse Current	I _r	V _r =5V	0	0	1	μA
Viewing Angle	2 θ 1/2	I _f =300mA	118	120	122	deg



- Note:** 1. IV is measured with an accuracy of $\pm 5\%$
 2. Forward voltage is measured with an accuracy of $\pm 0.1V$

[Temperature-profile (Surface of circuit board)]
 Use the conditions shown to the under figure.



[Recommended soldering pad design]
 Use the following conditions shown in the figure.

Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound

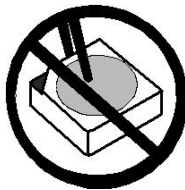


Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

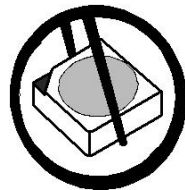
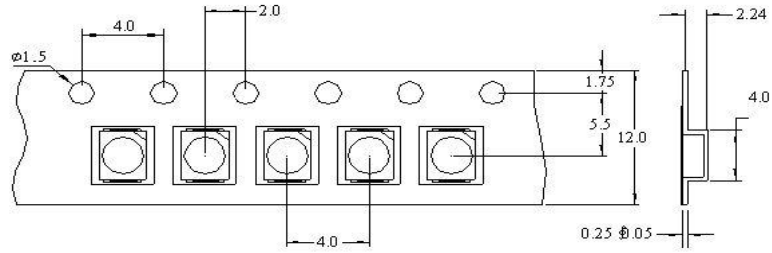


Figure 2

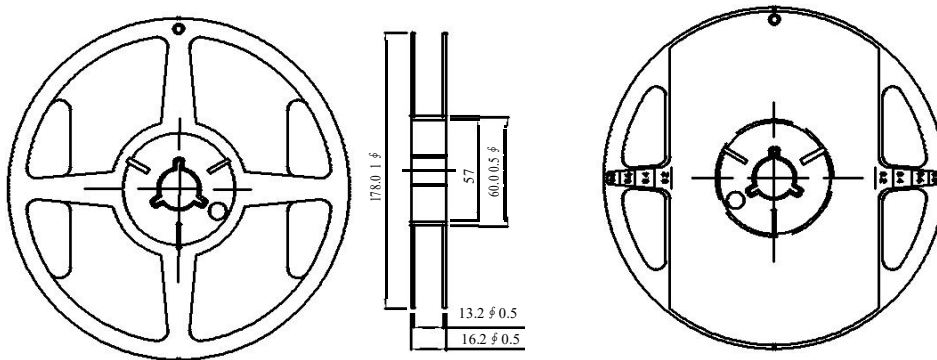
When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.



Dimensions for Tape

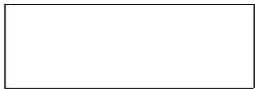


Dimensions for Reel

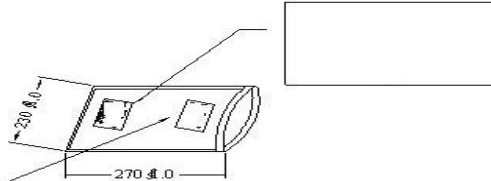


Packing

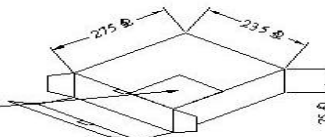
REEL
QUANTITY: 4 ,000 PCS



BAG
QUANTITY: 4 ,000 PCS



INSIDE BOX
QUANTITY: 4 BAGS
TOTAL 16 ,000 PCS



Notes:

- 1.All dimensions are in mm, tolerance is ± 2.0 mm unless otherwise noted.
- 2.Specifications are subject to change without notice.